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least two adjacent LEDs (2) at a prescribed distance (a),
and also associated connecting lines (4), wherein the
support (3) has a thermal conductivity of at least 1.5
W/Kxm.-

10/ (amended) The optoelectronic component group
according to Claim 9, wherein the support is composed of a
material which can be populated on said exterior mounting
surface by means of SMD technology.-

11 (amended) The optoelectronic component group
according to Claim 1, wherein the support is composed of a
material which is selected from the group consisting of
ceramic, non-conducting cermet, plastic and composite
material.-

12 (amended) The optoelectronic component group
according to Claim 9, wherein at least one further
component (7) is fixed on said exterior mounting surface.-

13 (amended) The optoelectronic component group
according to Claim 12, wherein the further component is an
integrated circuit.--

--6. (amended) The optoelectronic component group according to Claim 1, wherein the component group is a component part of a surface lighting luminaire or lamp.--

--7. (amended) The optoelectronic component group according to Claim 1, wherein a plurality of the the LEDs (2) are arranged regularly on the support.--

--8. (amended) The optoelectronic component group according to Claim 7, wherein the LEDs (2) form an array, with a prescribed distance (a and b) in the rows and columns, respectively.--

--9. (amended) The optoelectronic component group according to Claim 6, wherein the distance between the at least two adjacent LEDs is less than 2 mm.--

--10. (amended) The optoelectronic component group according to Claim 1, wherein the support is mounted on a further heat-dissipating, separate thermal plate.--

--11. (amended) The optoelectronic component group according to Claim 2, further comprising electronic

component parts integrated on said exterior mounting surface.--

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--12. (amended) The optoelectronic component group according to Claim 6, wherein a structural height of the group is less than 10 mm.--

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--13. (amended) An optoelectronic component group which is mounted on an exterior mounting surface of a support (3) and which comprises at least two adjacent LEDs (2), which are spaced apart from one another, and also associated connecting lines (4), wherein the support (3) dissipates heat well enough to realize a distance between adjacent LEDs of less than 2 mm, without limiting the specified forward current of the LEDs and without further aids.--

Add the following new claims.

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--14. The optoelectronic component group of claim 1, wherein said support has an exterior mounting surface and said at least two adjacent LEDs are mounted directly on said exterior mounting surface.

--15. An LED component group comprising:

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a support that has a thermal conductivity of at least 1.5 W/Kxm and that has an exterior mounting surface; plural LEDs mounted directly on said exterior mounting surface a distance between adjacent ones of said plural LEDs being no more than 5 mm; and connections for said plural LEDs mounted directly on said exterior mounting surface.

all

--¹³~~16~~. The LED component group of claim ¹⁴~~15~~, further comprising an integrated circuit mounted directly on said exterior mounting surface.

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--17. ¹⁵~~18~~ The LED component group of claim 15, wherein a packing density of said plural LEDs is at least 4 LEDs per square centimeter.

--¹⁶~~18~~. The LED component group of claim ¹⁴~~15~~, wherein said support comprises a material selected from the group of materials consisting of ceramic, non-conducting cermet, plastic, and composite material.

--¹⁷~~19~~. The LED component group of claim ¹⁴~~15~~, wherein said support has a thermal conductivity of at least 3 W/Kxm.--